



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Koos et al.

Attorney Docket No.:
NOVLP068/NVLS-000818

Application No.: 10/690,084

Examiner: UNASSIGNED

Filed: October 20, 2003

Group: 1763

Title: METHOD FOR FABRICATION OF
SEMICONDUCTOR INTERCONNECT
STRUCTURE WITH REDUCED
CAPACITANCE, LEAKAGE CURRENT, AND
IMPROVED BREAKDOWN VOLTAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on July 29, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Tara Hayden

SUPPLEMENTAL PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Before examination on its merits, please amend the above-identified patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begin on page 2 of this papers.

Remarks/Arguments begin on page 10 of this paper.

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01 FC:1202 450.00 OP
02 FC:1201 200.00 OP